

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, emplo



April 2013

FDMQ86530L

GreenBridgeTM Series of High-Efficiency Bridge Rectifiers N-Channel PowerTrench[®] MOSFET 60 V, 8 A, 17.5 m Ω

Features

- Max $r_{DS(on)}$ = 17.5 m Ω at V_{GS} = 10 V, I_D = 8 A
- Max $r_{DS(on)} = 23 \text{ m}\Omega$ at $V_{GS} = 6 \text{ V}$, $I_D = 7 \text{ A}$
- Max $r_{DS(on)}$ = 25 m Ω at V_{GS} = 4.5 V, I_D = 6.5 A
- Substantial efficiency benefit in PD solutions
- RoHS Compliant

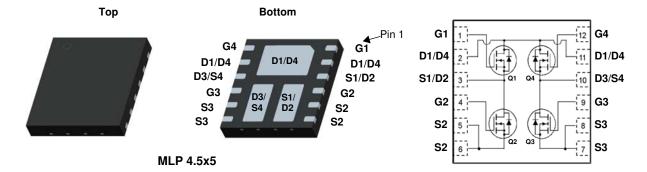


General Description

This Quad MOSFET solution provides ten-fold improvement in power dissipation over diode bridge.

Applications

- Active bridge
- Diode Bridge replacement in 24V & 48V AC systems



MOSFET Maximum Ratings TA = 25 °C unless otherwise noted

| Symbol | Paramet | Ratings | Units | | | |
|-----------------------------------|--|------------------------|-----------|-------------|----|--|
| V_{DS} | Drain to Source Voltage | | | 60 | V | |
| V_{GS} | Gate to Source Voltage | | | ±20 | V | |
| | Drain Current -Continuous | T _C = 25 °C | | 8 | | |
| I _D | -Continuous | T _A = 25 °C | (Note 1a) | 8 | Α | |
| | -Pulsed | | | 50 | 1 | |
| D | Power Dissipation | T _C = 25 °C | | 22 | w | |
| P_{D} | Power Dissipation | T _A = 25 °C | (Note 1a) | 1.9 | VV | |
| T _J , T _{STG} | Operating and Storage Junction Temperature Range | | | -55 to +150 | °C | |

Thermal Characteristics

| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | (Note 1a) | 65 | °C/W |
|-----------------|---|-----------|-----|------|
| $R_{\theta JA}$ | Thermal Resistance, Junction to Ambient | (Note 1b) | 135 | C/VV |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|------------|-----------|-----------|------------|------------|
| FDMQ86530L | FDMQ86530L | MLP 4.5x5 | 13 " | 12 mm | 3000 units |

Electrical Characteristics $T_J = 25$ °C unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Тур | Max | Units |
|--|--|---|-----|-----|------|-------|
| Off Chara | cteristics | | | | | |
| BV_{DSS} | Drain to Source Breakdown Voltage | $I_D = 250 \mu A, V_{GS} = 0 V$ | 60 | | | V |
| $\frac{\Delta BV_{DSS}}{\Delta T_{J}}$ | Breakdown Voltage Temperature Coefficient | I_D = 250 μ A, referenced to 25 °C | | 27 | | mV/°C |
| I _{DSS} | Zero Gate Voltage Drain Current | V _{DS} = 48 V, V _{GS} = 0 V | | | 1 | μΑ |
| I _{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$ | | | ±100 | nA |

On Characteristics

| $V_{GS(th)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}, I_D = 250 \mu A$ | 1 | 1.8 | 3 | V |
|--|---|--|---|-----|------|-------|
| $\frac{\Delta V_{GS(th)}}{\Delta T_J}$ | Gate to Source Threshold Voltage Temperature Coefficient | I_D = 250 μ A, referenced to 25 °C | | -6 | | mV/°C |
| r _{DS(on)} Static Drain to Source On Resistance | | $V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}$ | | 12 | 17.5 | - mΩ |
| | Otatia Dusin ta Osama Osa Dasiatana | $V_{GS} = 6 \text{ V}, I_D = 7 \text{ A}$ | | 15 | 23 | |
| | Static Drain to Source On Resistance | $V_{GS} = 4.5 \text{ V}, I_D = 6.5 \text{ A}$ | | 20 | 25 | |
| | | $V_{GS} = 10 \text{ V}, I_D = 8 \text{ A}, T_J = 125 \text{ °C}$ | | 18 | 26 | |
| 9 _{FS} | Forward Transconductance | V _{DS} = 5 V, I _D = 8 A | | 28 | | S |

Dynamic Characteristics

| C _{iss} | Input Capacitance | V 20 V V 0 V | 1725 | 2295 | pF |
|------------------|------------------------------|--|------|------|----|
| C _{oss} | Output Capacitance | $V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V},$ $f = 1 \text{ MHz}$ | 299 | 400 | pF |
| C _{rss} | Reverse Transfer Capacitance | 1 - 1 10112 | 10 | 15 | pF |

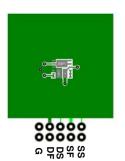
Switching Characteristics

| $t_{d(on)}$ | Turn-On Delay Time | | 8.8 | 18 | ns |
|---------------------|-------------------------------|---|-----|----|----|
| t _r | Rise Time | V _{DD} = 30 V, I _D = 8 A, | 3.8 | 10 | ns |
| t _{d(off)} | Turn-Off Delay Time | V_{GS} = 10 V, R_{GEN} = 6 Ω | 22 | 35 | ns |
| t _f | Fall Time | | 2.8 | 10 | ns |
| Q_{g} | Total Gate Charge | V _{GS} = 0 V to 10 V | 23 | 33 | nC |
| Q_{g} | Total Gate Charge | $V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $V_{DD} = 30 \text{ V},$ | 11 | 16 | nC |
| Q_{gs} | Gate to Source Charge | I _D = 8 A | 5.1 | | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | | 2.3 | | nC |

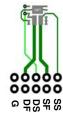
Drain-Source Diode Characteristics

| V _{SD} | Source to Drain Diode Forward Voltage | $V_{GS} = 0 \text{ V}, I_{S} = 8 \text{ A}$ (Note 2) | | 0.8 | 1.3 | V |
|-----------------|---|--|--|-----|-----|----------|
| | Source to Drain Diode 1 of ward voltage | $V_{GS} = 0 \text{ V}, I_S = 1.6 \text{ A}$ (Note 2) | | 0.7 | 1.2 | ' |
| t _{rr} | Reverse Recovery Time | I _F = 8 A, di/dt = 100 A/μs | | 27 | 43 | ns |
| Q _{rr} | Reverse Recovery Charge | IF = 8 A, αι/αι = 100 A/μs | | 12 | 22 | nC |

^{1.} $R_{\theta,M}$ is determined with the device mounted on a 1in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta,JC}$ is guaranteed by design while $R_{\theta,CA}$ is determined by the user's board design.



a. 65 °C/W when mounted on a 1 in 2 pad of 2 oz copper. the board designed Q1+Q3 or Q2+Q4.



b. 135 °C/W when mounted on a minimum pad of 2 oz copper. the board designed Q1+Q3 or Q2+Q4.

^{2.} Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.

Typical Characteristics T_J = 25 °C unless otherwise noted

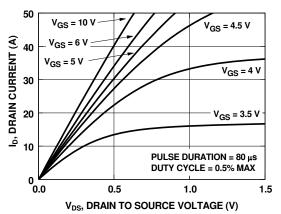


Figure 1. On-Region Characteristics

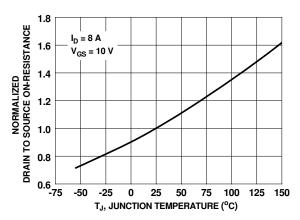


Figure 3. Normalized On-Resistance vs Junction Temperature

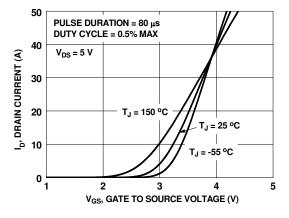


Figure 5. Transfer Characteristics

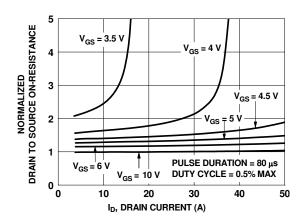


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

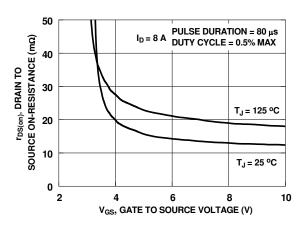


Figure 4. On-Resistance vs Gate to Source Voltage

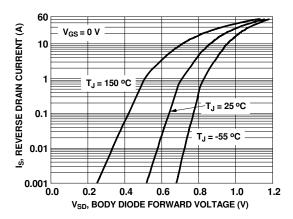


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics $T_J = 25$ °C unless otherwise noted

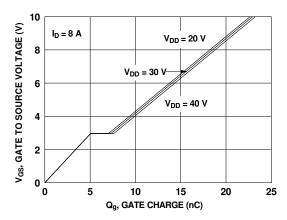


Figure 7. Gate Charge Characteristics

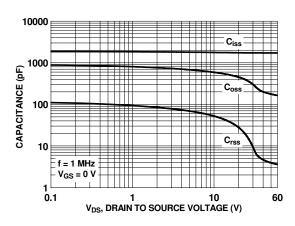


Figure 8. Capacitance vs Drain to Source Voltage

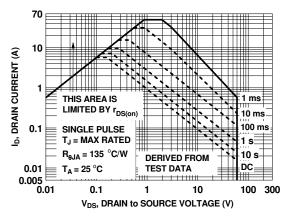


Figure 9. Forward Bias Safe Operating Area

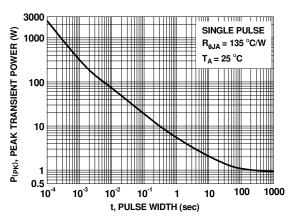


Figure 10. Single Pulse Maximum Power Dissipation

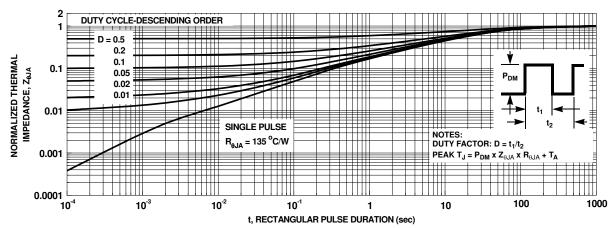
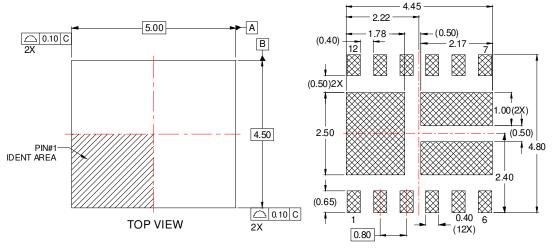
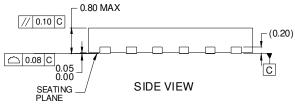
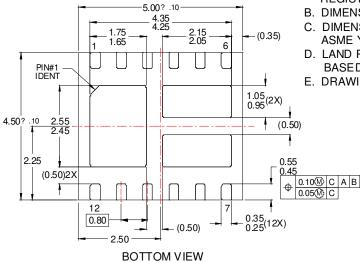


Figure 11. Junction-to-Ambient Transient Thermal Response Curve

Dimensional Outline and Pad Layout







NOTES:
A THIS MKT. DWG. DOES NOT FULLY CONFORM TO JEDEC MO-229 REGISTRATION

RECOMMENDED LAND PATTERN

- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
- D. LAND PATTERN RECOMMENDATION IS BASED ON FSC DESIGN ONLY.
- E. DRAWING FILENAME: MKT-MLP12FRev1.





TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

2Cool™ AccuPower™ AX-CAP®* BitSiC™ Build it Now™ CorePLUS™ CorePOWER™

CROSSVOLT™ $\mathsf{CTL^{\mathsf{TM}}}$ Current Transfer Logic™

DEUXPEED® Dual Cool™ EcoSPARK® EfficentMax™ ESBC™

Fairchild®

Fairchild Semiconductor® FACT Quiet Series™

FAST® FastvCore™ FETBench™ **FPS™** F-PFS™ FRFET®

Global Power ResourceSM

Green Bridge™ Green FPS™ Green FPS™ e-Series™

G*max*™ GTO™

IntelliMAX™ ISOPLANAR™

Marking Small Speakers Sound Louder

and Better™ MegaBuck™

MIČROCOUPLER™ MicroFET™ MicroPak™

MicroPak2™ $MillerDrive^{TM}$ MotionMax™ mWSaver™ OptoHiT™ OPTOLOGIC® OPTOPLANAR® PowerTrench® PowerXS™

Programmable Active Droop™

OFFT[®] QSTM Quiet Series™ RapidConfigure™

тм

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

STEALTH™ SuperFET® SuperSOT™-3 SuperSOT™-6 SuperSOT™-8 SupreMOS® SyncFET™

Sync-Lock™ SYSTEM®' 5GENERAL TinyBoost TinyBuck™ TinyCalc™ TinyLogic[®] TINYOPTO™ TinyPower™ TinyPWM™ TinyWire™ TranSiC® TriFault Detect™ TRUECURRENT®*

UHC® Ultra FRFFT™ UniFET™ VCX™ VisualMaxTM VoltagePlus™ XS™

uSerDes™

*Trademarks of System General Corporation, used under license by Fairchild Semiconductor

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

LIFE SUPPORT POLICY
FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE
EXPRESS WRITTEN APPROVAL OF FAIRCHILD SEMICONDUCTOR CORPORATION.

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury of the user.
- A critical component in any component of a life support, device, or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.Fairchildsemi.com, under Sales Support.

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufactures of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed application, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handing and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address and warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

PRODUCT STATUS DEFINITIONS **Definition of Terms**

| Datasheet Identification | Product Status | Definition |
|---|-------------------|---|
| Advance Information Formative / In Design | | Datasheet contains the design specifications for product development. Specifications may change in any manner without notice. |
| Preliminary First Production | | Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design. |
| No Identification Needed | Full Production | Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design. |
| Obsolete | Not In Production | Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only. |

Rev. 164

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor nessure any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, a

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800–282–9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81–3–5817–1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative